DRM (S-PVSON-N8)  PLASTIC SMALL OUTLINE NO-LEAD

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
B. This drawing is subject to change without notice.
C. SON (Small Outline No-Lead) package configuration.

⚠️ The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
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